

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HIROYUKI NAKAMURA	07/24/2015
MUSUBU ICHIKAWA	07/31/2015
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<b>City:</b>	UEDA-SHI, NAGANO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	386-0498
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14770600
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<b>SIGNATURE:</b>	/Daniel P. Lent/

<b>DATE SIGNED:</b>	08/26/2015
<b>Total Attachments: 2</b> source=7G22435#page1.tif source=7G22435#page2.tif	

## ASSIGNMENT

WHEREAS We, **Hiroyuki NAKAMURA** c/o **SHINANO KENSHI CO., LTD.**,  
**1078, Kami-maruko, Ueda-shi, Nagano 386-0498 Japan** and **Musubu ICHIKAWA** c/o  
**Faculty of Textile Science and Technology, Shinshu University, 3-15-1, Tokida, Ueda-shi,**  
**Nagano 386-8567 Japan**, (hereinafter referred to as "ASSIGNORS") have invented certain  
new and useful improvements in:

### **INFORMATION-READING COMPONENT AND INFORMATION-READING DEVICE UTILIZING SAME**

which claims priority to **Japanese Application No. 2013-039685**, filed **February 28, 2013**,  
and for which I am about to file or have filed an application for Letters Patent of the United  
States;

AND WHEREAS, **SHINANO KENSHI CO., LTD.** (hereinafter referred to as  
"ASSIGNEES"), a corporation organized and existing under the laws of the Country of **Japan**,  
having a place of business at **1078, Kami-maruko, Ueda-shi, Nagano 386-0498 Japan**, and,  
**SHINSHU UNIVERSITY** (hereinafter referred to as "ASSIGNEES"), a corporation  
organized and existing under the laws of the Country of **Japan**, having a place of business at  
**3-1-1, Asahi, Matsumoto-shi, Nagano 390-0802 Japan**, are desirous of acquiring an interest  
in the United States and all foreign countries, in and to the said invention and Letters Patent to  
be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for  
good and valuable consideration, the receipt of which is hereby acknowledged, We, the said  
ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said  
ASSIGNEES, the entire right, title and interest in and to said invention, the applications, and  
any and all patents that may be issued therefrom, in the United States and in all foreign  
countries, including any and all revivals, refilings, continuations, continuations-in part,  
divisions, and reissues thereof, to the said ASSIGNEES; and we, the ASSIGNORS , do  
hereby agree that we will execute all papers necessary in connection with the United States and  
foreign applications when called upon to do so by the said ASSIGNEES, its successors or  
assigns, and that We will, at the cost and expense of the said ASSIGNEES fully assist and

cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: July 24, 2015

Hiroyuki Nakamura L.S.  
Hiroyuki NAKAMURA

Date: July 31, 2015

Musubu Ichikawa L.S.  
Musubu ICHIKAWA